

Materials for interconnection structures —

**Part 5: Sectional specification set for
conductive foils and films with and
without coatings —**

**Section 1: Copper foils (for the
manufacture of copper-clad base
materials)**

The European Standard EN 61249-5-1:1996 has the status of a
British Standard

ICS 31.180

Committees responsible for this British Standard

The preparation of this British Standard was entrusted to Technical Committee EPL/52, Printed circuits, upon which the following bodies were represented:

- British Telecommunications plc
- Electrical and Electronic Industries Association (BEAMA Ltd.)
- Federation of the Electronics Industries
- GAMBICA (BEAMA Ltd.)
- Institute of Metal Finishing
- National Supervisory Inspectorate
- Printed Circuit Interconnection Federation
- Surface Mount and Related Technologies (SMART Group)

This British Standard, having been prepared under the direction of the Electrotechnical Sector Board, was published under the authority of the Standards Board and comes into effect on 15 September 1996

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The following BSI references relate to the work on this standard
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National foreword

This British Standard has been prepared by Technical Committee EPL/52 and is the English language version of EN 61249-5-1:1996, *Materials for interconnection structures — Part 5: Sectional specification set for conductive foils and films with and without coatings. Section 1: Copper foils (for the manufacture of copper-clad base materials)*, published by the European Committee for Electrotechnical Standardization (CENELEC). It is identical with IEC 1249-5-1:1995 published by the International Electrotechnical Commission (IEC).

Cross-reference

Publication referred to	Corresponding British Standard
ISO 4287-1:1984	BS 6741 <i>Glossary of surface roughness terms</i> Part 1:1987 <i>Surface and its parameters</i>

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the EN title page, pages 2 to 12, an inside back cover and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

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Descriptors: Printed circuits, interconnection structures, conductive foils and films, coatings, copper-clad base materials, flexible materials

English version

Materials for interconnection structures
Part 5: Sectional specification set for conductive foils and
films with and without coatings
Section 1: Copper foils (for the manufacture of copper-clad
base materials)

(IEC 1249-5-1:1995)

Matériaux pour les structures d'interconnexion
Partie 5: Collection de spécifications
intermédiaires pour feuilles et films
conducteurs avec ou sans revêtement
Section 1: Feuilles de cuivre (pour la fabrication
de matériaux de base plaqués cuivre)
(CEI 1249-5-1:1995)

Materialien für Verbindungsstrukturen
Teil 5: Rahmenspezifikation für leitfähige
Folien mit und ohne Beschichtungen
Hauptabschnitt 1: Kupfer-Foilen (zur
Herstellung von kupferkaschierten
Basismaterialien
(IEC 1249-5-1:1995)

This European Standard was approved by CENELEC on 1995-11-28. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

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Foreword

The text of document 52/544/DIS, future edition 1 of IEC 1249-5-1, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61249-5-1 on 1995-11-28.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1996-09-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 1996-09-01

Annexes designated “normative” are part of the body of the standard. Annexes designated “informative” are given for information only. In this standard, annex A is normative and annex B is informative.

The following publication is quoted in this standard:

ISO 4287-1:1984 *Surface roughness — Terminology — Part 1: Surface and its parameters.*

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